

Method for conductively connecting a component
on a transparent substrate

Abstract

The invention relates to a method to conductively connect an electrical component with at least one conductive layer, whereby the conductive layer is applied to a substrate which is essentially transparent in the visible wavelength zone of light, comprising the following steps:

- the electrical component or the conductive layer is provided with a soldering material in the area where the component is to be connected to the conductive layer;
- the soldering material is provided with energy supplied by an energy source, such that
- the soldering material melts and a non-detachable, material-bonded conductive connection between the electrical component and the conductive layer is established.